

1. General description

Planar passivated Silicon Controlled Rectifier in a SOT78 (TO-220AB) plastic package intended for use in applications requiring very high inrush current capability and high thermal cycling performance.

2. Features and benefits

- High thermal cycling performance
- High voltage capability
- Planar passivated for voltage ruggedness and reliability
- Very high current surge capability

3. Applications

- Ignition circuits
- Motor control
- Protection circuits e.g. SMPS inrush current
- Voltage regulation

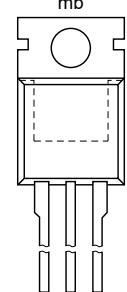
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	-	800	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 103^\circ C$; Fig. 1	-	-	13	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; Fig. 2 ; Fig. 3	-	-	20	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25^\circ C$; $t_p = 10\text{ ms}$; Fig. 4 ; Fig. 5	-	-	200	A
		half sine wave; $T_{j(init)} = 25^\circ C$; $t_p = 8.3\text{ ms}$	-	-	220	A
T_j	junction temperature		-	-	125	$^\circ C$
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25^\circ C$; Fig. 7	-	3	32	mA
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 536\text{ V}$; $T_j = 125^\circ C$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit; Fig. 12	200	300	-	$V/\mu s$

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
3	G	gate		
mb	A	mounting base; connected to anode	 TO-220AB (SOT78)	

6. Ordering information

Table 3. Ordering information

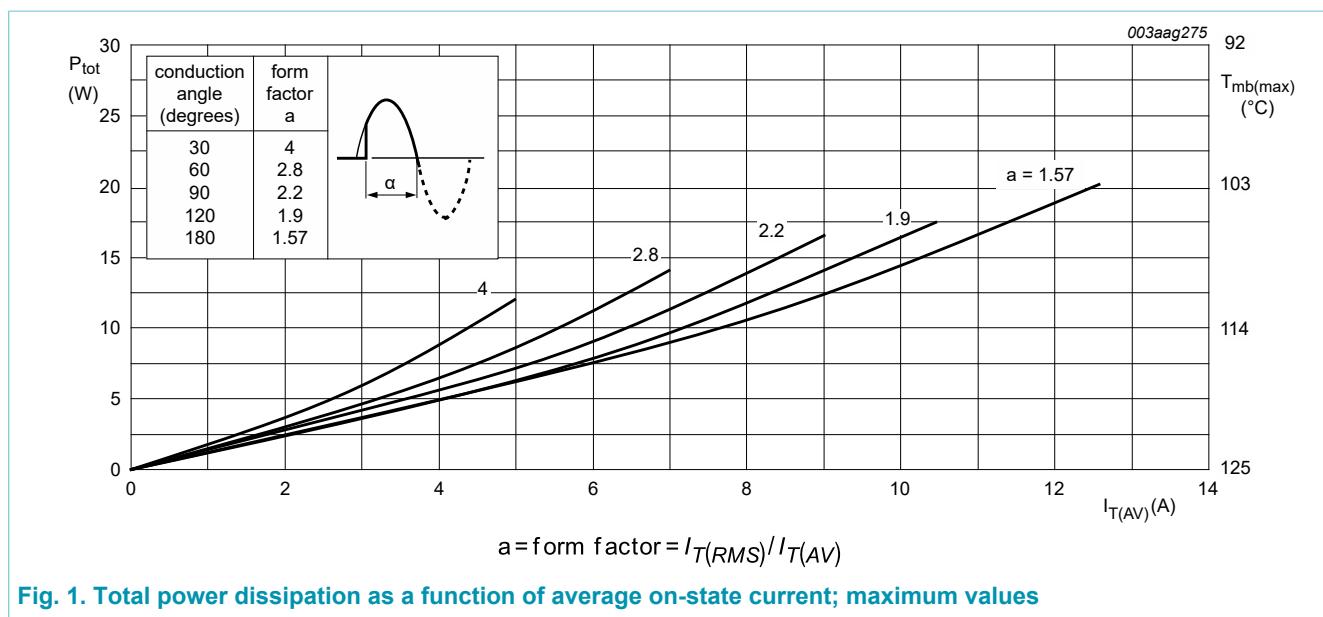
Type number	Package			Version
	Name	Description		
BT152-800R	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB		SOT78

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	800	V
V_{RRM}	repetitive peak reverse voltage		-	800	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 103^{\circ}\text{C}$; Fig. 1	-	13	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; Fig. 2 ; Fig. 3	-	20	A
	non-repetitive peak on-state current	half sine wave; $T_{j(\text{init})} = 25^{\circ}\text{C}$; $t_p = 10\text{ ms}$; Fig. 4 ; Fig. 5	-	200	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; SIN	-	220	A ² s
			-	200	A/ μ s
dI_T/dt	rate of rise of on-state current	$I_G = 100\text{ mA}$	-	5	A
I_{GM}	peak gate current		-	200	A
V_{RGM}	peak reverse gate voltage		-	0.5	V
P_{GM}	peak gate power		-	150	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	20	W
T_{stg}	storage temperature		-40	125	°C
T_j	junction temperature		-	125	°C



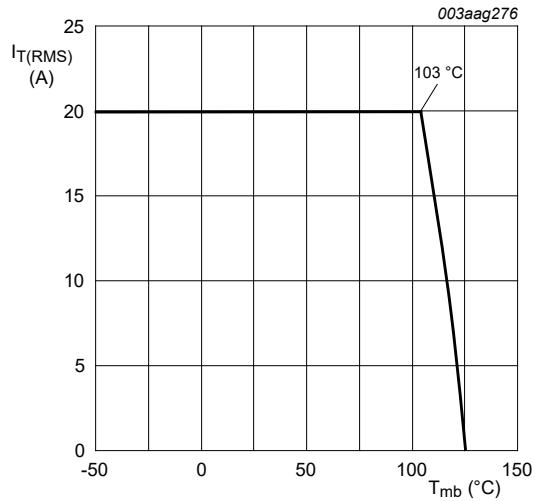
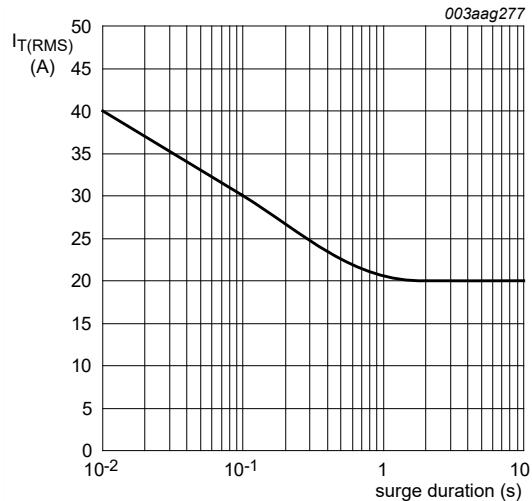
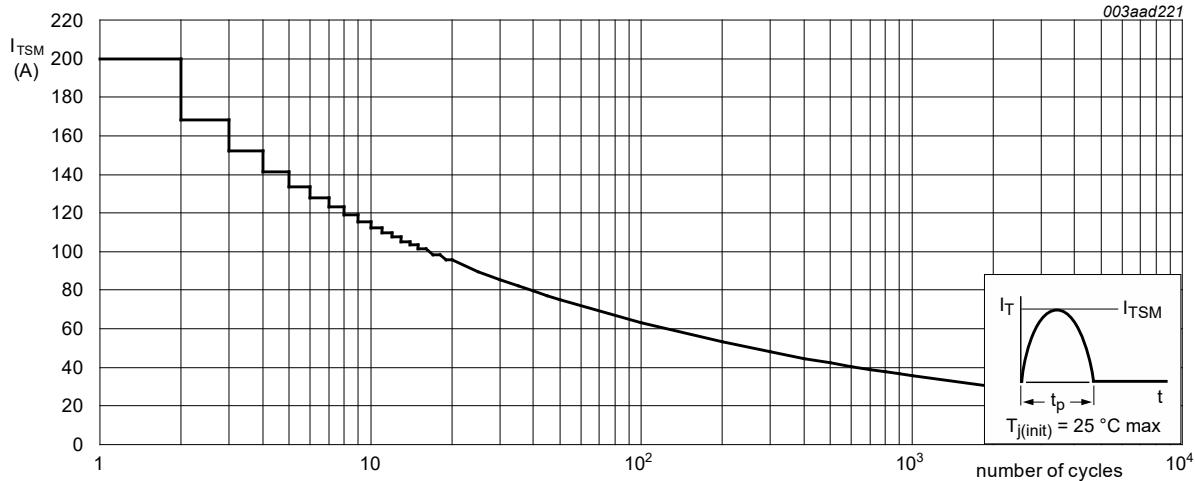


Fig. 2. RMS on-state current as a function of mounting base temperature; maximum values



f = 50 Hz; T_{mb} = 103 °C

Fig. 3. RMS on-state current as a function of surge duration; maximum values



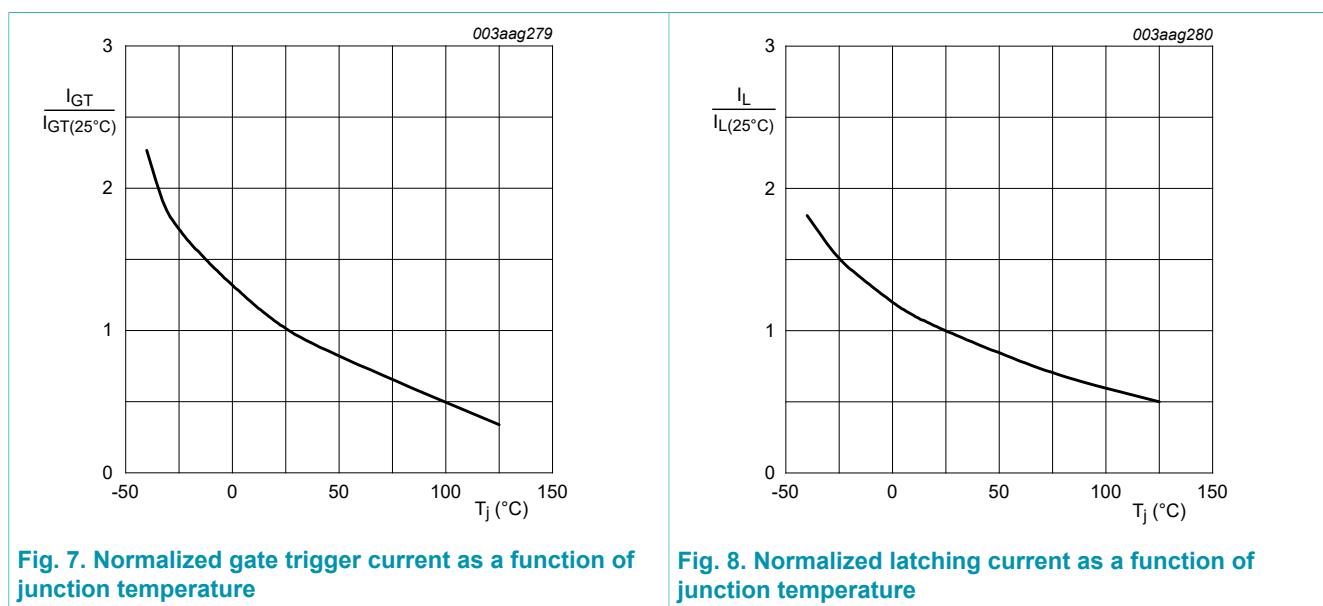
f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

8. Characteristics

Table 5. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	$V_D = 12 \text{ V}$; $I_T = 0.1 \text{ A}$; $T_j = 25^\circ\text{C}$; Fig. 7		-	3	32	mA
I_L	latching current	$V_D = 12 \text{ V}$; $I_G = 0.1 \text{ A}$; $T_j = 25^\circ\text{C}$; Fig. 8		-	25	80	mA
I_H	holding current	$V_D = 12 \text{ V}$; $T_j = 25^\circ\text{C}$; Fig. 9		-	15	60	mA
V_T	on-state voltage	$I_T = 40 \text{ A}$; $T_j = 25^\circ\text{C}$; Fig. 10		-	1.4	1.75	V
V_{GT}	gate trigger voltage	$V_D = 12 \text{ V}$; $I_T = 0.1 \text{ A}$; $T_j = 25^\circ\text{C}$; Fig. 11		-	0.6	1	V
		$V_D = 800 \text{ V}$; $I_T = 0.1 \text{ A}$; $T_j = 125^\circ\text{C}$		0.25	0.4	-	V
I_D	off-state current	$V_D = 800 \text{ V}$; $T_j = 125^\circ\text{C}$		-	0.2	1	mA
I_R	reverse current	$V_R = 800 \text{ V}$; $T_j = 125^\circ\text{C}$		-	0.2	1	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 536 \text{ V}$; $T_j = 125^\circ\text{C}$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit; Fig. 12		200	300	-	V/ μ s
t_{gt}	gate-controlled turn-on time	$I_{TM} = 40 \text{ A}$; $V_D = 800 \text{ V}$; $I_G = 100 \text{ mA}$; $dI_G/dt = 5 \text{ A}/\mu\text{s}$		-	2	-	μ s
t_q	commutated turn-off time	$V_{DM} = 536 \text{ V}$; $T_j = 125^\circ\text{C}$; $I_{TM} = 50 \text{ A}$; $V_R = 25 \text{ V}$; $(dI_T/dt)_M = 30 \text{ A}/\mu\text{s}$; $dV_D/dt = 50 \text{ V}/\mu\text{s}$; $R_{GK(ext)} = 100 \Omega$; ($V_{DM} = 67\%$ of V_{DRM})		-	70	-	μ s



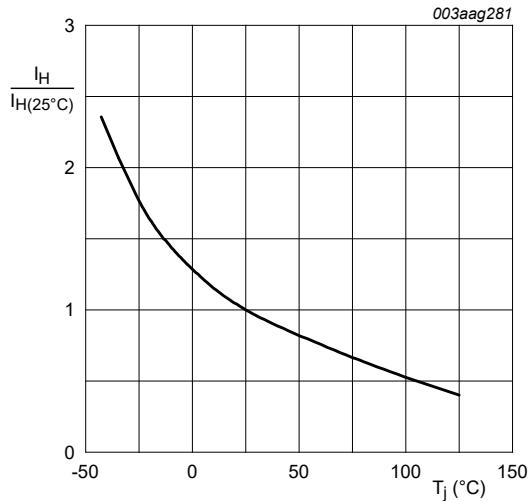


Fig. 9. Normalized holding current as a function of junction temperature

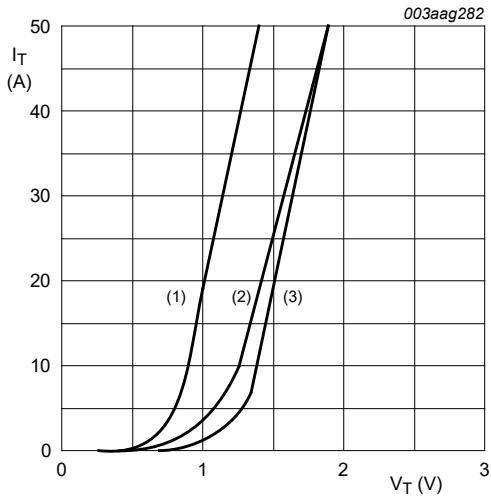


Fig. 10. On-state current as a function of on-state voltage

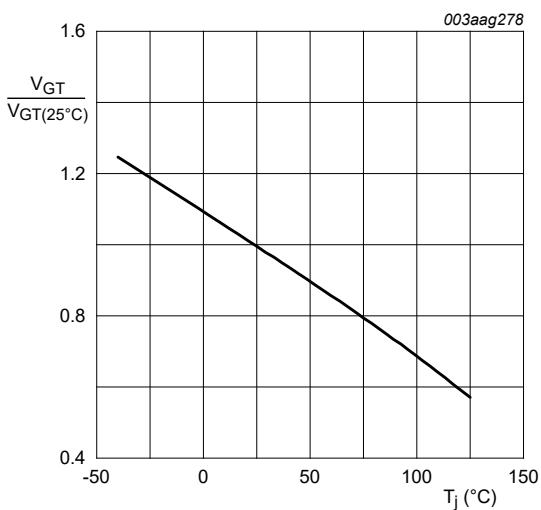


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

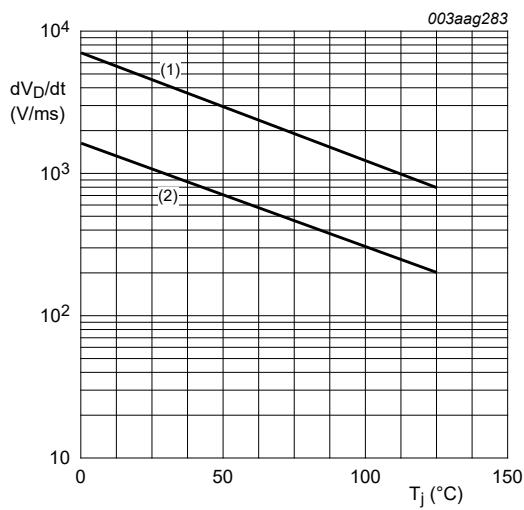
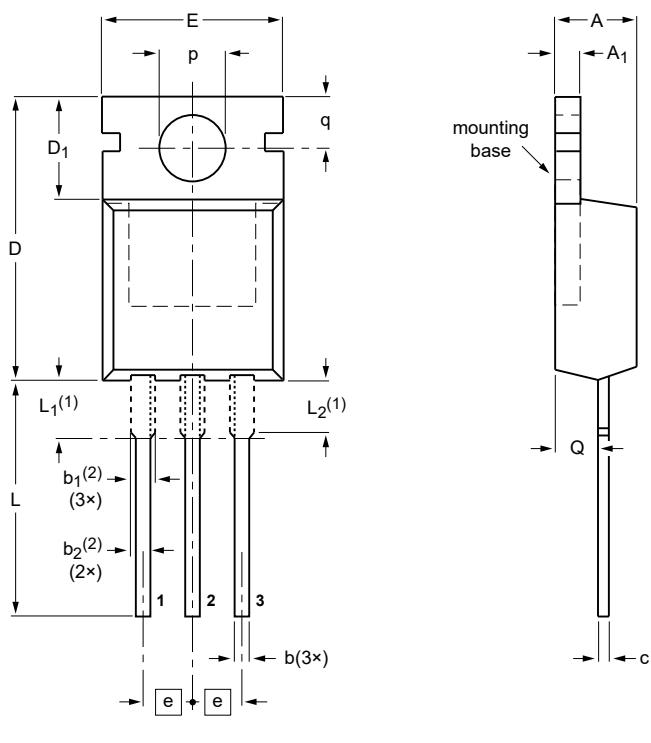


Fig. 12. Critical rate of rise of off-state voltage as a function of junction temperature; typical values

9. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



0 5 10 mm
scale

DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	b ₁₍₂₎	b ₂₍₂₎	c	D	D ₁	E	e	L	L ₁₍₁₎	L ₂₍₁₎ max.	p	q	Q
mm	4.7	1.40	0.9	1.6	1.3	0.7	16.0	6.6	10.3	2.54	15.0	3.30	3.0	3.8	3.0	2.6
	4.1	1.25	0.6	1.0	1.0	0.4	15.2	5.9	9.7		12.8	2.79		3.5	2.7	2.2

Notes

1. Lead shoulder designs may vary.
2. Dimension includes excess dambar.

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